

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3676257

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SUSUMU TAUCHI	12/04/2015
	TAKASHI UEMURA	12/04/2015
	KOHEI SATO	12/03/2015
RECEIVING PARTY DATA		
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	
Street Address:	24-14, NISHI-SHIMBASHI 1-CHOME	
City:	MINATO-KU, TOKYO	
State/Country:	JAPAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	29544070
CORRESPONDENCE DATA		
Fax Number:	(202)628-8844	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	2026242500	
Email:	ggoodin@crowell.com	
Correspondent Name:	CROWELL & MORING LLP	
Address Line 1:	1001 PENNSYLVANIA AVENUE, NW	
Address Line 4:	WASHINGTON, D.C. 20004-2595	
ATTORNEY DOCKET NUMBER:	108353.25923US	
NAME OF SUBMITTER:	RICHARD R. DIEFENDORF	
SIGNATURE:	/Richard R. Diefendorf, Reg. No. 32,390/	
DATE SIGNED:	12/30/2015	
Total Attachments: 1		
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ELECTRODE COVER FOR A PLASMA PROCESSING APPARATUS

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full and of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Shunichi Zouki</u>	<u>12/4/2015</u>
2) <u>Takashi Hamura</u>	<u>12/4/2015</u>
3) <u>Kohsei Sato</u>	<u>12/3/2015</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____